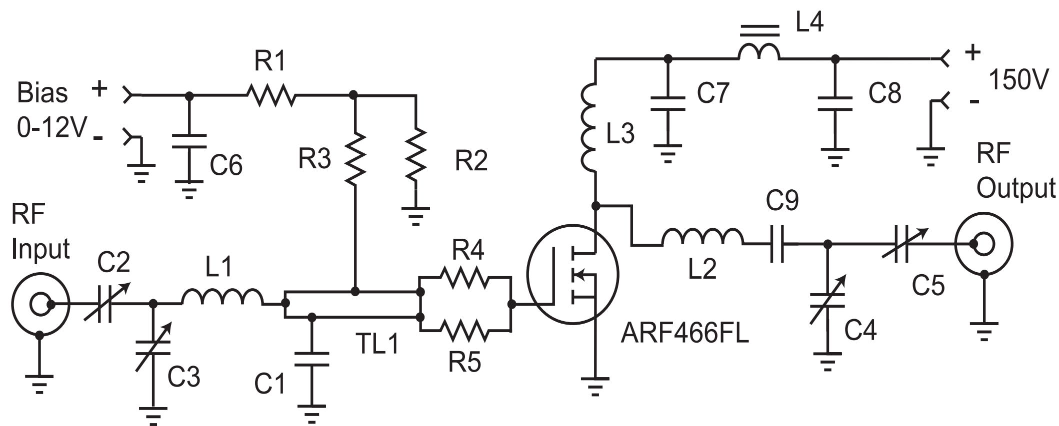
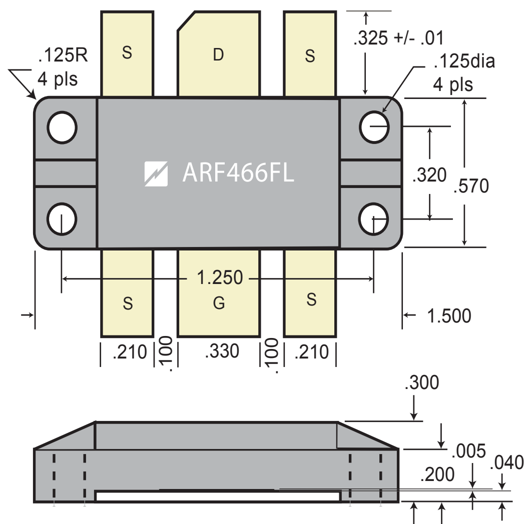
*G Denotes RoHS Compliant. Pb Free Terminal Finish.

40.68 MHz Test Circuit



C1 -- 2200 pF ATC 700B	L1 -- 3t #22 AWG .25"ID .25 "L ~55nH	R1- R3 -- 1k Ω 0.5W
C2-C5 -- Arco 465 Mica trimmer	L2 -- 5t #16 AWG .312" ID .35"L ~176nH	R4- R5 -- 1Ω 1W SMT
C6-C8 -- .1 mF 500V ceramic chip	L3 -- 10t #24 AWG .25"ID ~.5uH	TL1 -- 40 Ω t-line 0.15 x 2"
C9 -- 3x 2200 pF 500V chips COG	L4 -- VK200-4B ferrite choke 3uH	C1 is ~1.75" from R4-5.

T3 Package Outline



Thermal Considerations and Package Mounting:

The rated power dissipation is only available when the package mounting surface is at 25°C and the junction temperature is 175°C. The thermal resistance between junctions and case mounting surface is 0.13 °C/W. When installed, an additional thermal impedance of 0.17°C/W between the package base and the mounting surface is typical. Insure that the mounting surface is smooth and flat. Thermal joint compound must be used to reduce the effects of small surface irregularities. Use the minimum amount necessary to coat the surface. The heatsink should incorporate a copper heat spreader to obtain best results.

The package design clamps the ceramic base to the heatsink. A clamped joint maintains the required mounting pressure while allowing for thermal expansion of both the base and the heat sink. Four 4-40 (M3) screws provide the required mounting force. Torque the mounting screws to 7 LQOE(0.8 N-m).

HAZARDOUS MATERIAL WARNING

The white ceramic portion of the device between leads and mounting surface is beryllium oxide, BeO. Beryllium oxide dust is toxic when inhaled. Care must be taken during handling and mounting to avoid damage to this area. These devices must never be thrown away with general industrial or domestic waste.